



专业铸就品质
专注创造价值

PROFESSIONALISM FORGES QUALITY
FOCUS ON CREATING VALUE

压合耐高温
材料生产厂家

MANUFACTURER OF PRESSED HIGH-TEMPERATURE
RESISTANT MATERIALS



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深圳市环宇昌电子有限公司
Shenzhen Huanyuchang Electronics Co., Ltd



压合耐高温材料生产厂家

服务于 CCL、PCB、FPCB、铝基板以及
新能源等行业

**MANUFACTURER OF PRESSED HIGH-TEMPERATURE
RESISTANT MATERIALS**

Serving CCL PCB、FPCB、Aluminum substrate and new
energy industries

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专业铸就品质
专注创造价值

PROFESSIONALISM FORGES QUALITY
FOCUS ON CREATING VALUE

环宇昌电子有限公司，成立于2009年，位于广东省深圳市，是一家集研发、生产、销售于一体的综合性企业。随着公司战略规划的实施，成立了以华南为市场的“深圳市环宇昌电子有限公司”，和以华东为市场的“苏州市深宇晟电子有限公司”，以及以华中为生产基地的“河南环宇昌电子科技有限公司”。

作为一家综合实力较强的高新科技企业，环宇昌专注于线路板压合制程周边材料的开发与经营，同时，在高温缓冲垫领域也取得显著成就。公司拥有先进的生产配套设备及耐高温材料生产技术，主要产品包括：耐高温缓冲垫、进口承载盘、进口钢板、耐高温膜等四个系列，目前公司产品被广泛应用于PCB、FPCB、CCL、铝基板、新能源等领域。

行稳路远，专业铸就品质，专注创造价值！环宇昌将继续精研制造，为客户提供更专业的压合耐高温材料与定制化应用服务，立志成为客户最坚实的后盾，成为电子行业的领导者！

Huan Yuchang Electronics Co., Ltd., established in 2009, is located in Shenzhen, Guangdong Province. It is a comprehensive enterprise that integrates research and development, production, and sales. With the implementation of the company's strategic plan, "Shenzhen Huanyu Chang Electronics Co., Ltd." targeting the South China market, "Suzhou Shenyu Sheng Electronics Co., Ltd." targeting the East China market, and "Henan Huanyu Chang Electronic Technology Co., Ltd." targeting the Central China production base have been established.

As a high-tech enterprise with strong comprehensive strength, Huan Yuchang focuses on the development and operation of peripheral materials for circuit board lamination process, and has also achieved significant achievements in the field of high-temperature buffer pads. The company has advanced production supporting equipment and high-temperature resistant material production technology. Its main products include four series: high-temperature resistant buffer pads, imported bearing discs, imported steel plates, high-temperature resistant films, etc. Currently, the company's products are widely used in PCB FPCB, CCL, Aluminum substrate, new energy and other fields.

Steady journey ahead, professionalism forges quality, and focus on creating value! Huan Yuchang will continue to focus on research and manufacturing, providing customers with more professional pressed high-temperature resistant materials and customized application services. We are determined to become the most solid support for our customers and a leader in the electronics industry!

15⁺年

专注压合耐高温材料
生产定制经验

80000⁺平方米

现代化生产厂房

100⁺家

电子 / 新能源行业合作商

3个

生产基地

COMPANY CULTURE

企业文化



以品质至上，亮剑市场，鏖战群雄， 誓做电子行业的领导者

Putting quality first, shining the sword in the market, fiercely fighting against the heroes,
Swearing to be a leader in the electronics industry



我们的愿景
Our Vision

**努力成为电子行业
顶级材料供应商**
Strive to become a top material
supplier in the electronics industry



我们的使命
Our mission

**为客户解决问题是
我们最大的骄傲**
Solving problems for customers is
our greatest pride



我们的价值观
Our values

**团结拼搏 务实求新
努力进取 品质第一**
Unity, hard work, pragmatism,
innovation, striving for progress,
quality first



COMPANY HONORS

公司荣誉



QUALITY

SPEAK WITH AUTHORITY
PROFESSIONAL QUALITY WITNESS HONOR

用权威说话 专业品质 见证荣誉

COMPANY HISTORY

公司历程



砥砺前行，不忘初心

创新引领未来，发展见证辉煌

Forge ahead and never forget our original intention
Innovation leads the future, development witnesses glory

2009-2012

- 2009年深圳市环宇昌电子有限公司成立
- 2010年正式引进美国牛皮纸，做牛皮纸相关贸易
- 2012年组建一支优秀的研发团队，专注研发耐高温特种材料，高分子化学材料，润滑冷却材料及材料加工技术。
- Established in 2009, Shenzhen Huanyuchang Electronics Co., Ltd
- In 2010, American kraft paper was officially introduced for kraft paper related trade
- In 2012, an excellent R&D team was established, focusing on the research and development of high-temperature resistant special materials, polymer chemical materials, lubrication and cooling materials, and material processing technology.

2013-2015

- 2013年团队与中科院联合开发出食用级牛皮纸（TS纸）并持续量产。
- 2014年拓展华东市场成立苏州市深宇晟电子有限公司。
- 食用级牛皮纸（TS纸）获得 ISO9001 2015 质量管理体系认证书；
- In 2013, the team collaborated with the Chinese Academy of Sciences to develop edible grade kraft paper (TS paper) and continued mass production.
- In 2014, Suzhou Shenyusheng Electronics Co., Ltd. was established to expand into the East China market.
- Edible grade kraft paper (TS paper) has obtained ISO9001 2015 quality management system certification;

2016-2018

- 2016年成功对接日本冶金，开始国内电子行业钢板相关业务，并成立钢板部；
- 2017年全员投入电子缓冲垫研发与制作流程优化。
- 2018年成功研发高性能电子缓冲垫 -- 纳维斯垫
- In 2016, we successfully connected with Japanese metallurgy and started steel plate related business in the domestic electronics industry, and established a steel plate department;
- In 2017, all staff members invested in the research and development of electronic cushioning pads and optimized the production process.
- In 2018, we successfully developed high-performance electronic cushioning pad - NAWES MAT

2019-2022

- 2019年河南环宇昌电子科技有限公司奠基与建厂
- 2020年研发团队起草申报国家专利投稿30余件，获通过18件；被河南省评为高新技术企业；
- 2021年纳维斯垫获 ISO9001（2021）质量管理体系认证证书；
- 2022年环宇昌荣获“中国科学家论坛”科学进步奖
- In 2019, Henan Huanyuchang Electronic Technology Co., Ltd. laid the foundation and established the factory
- In 2020, the R&D team drafted and submitted over 30 national patent applications, of which 18 were approved; Rated as a high-tech enterprise by Henan Province;
- In 2021, Navis pads obtained ISO9001 (2021) quality management system certification;
- In 2022, Huan Yuchang won the "China Scientists Forum" Science Progress Award

2023-2025

- 2023年河南环宇昌携手黄淮学院签约就业实习仪式，为毕业生提供更多的就业岗位和机会。
- 2024年环宇昌工程二期完成竣工投入使用、新建膜材事业部
- 2025年环宇昌第三期基建工程正在火热筹备中
- In 2023, Henan Huanyuchang and Huanghuai College signed a contract for employment internships, providing more job opportunities and positions for graduates.
- The second phase of the Huanyuchang project will be completed and put into use in 2024, and a new membrane material business unit will be established
- The third phase of the infrastructure project of Huan Yuchang in 2025 is currently in the hot preparation stage

ENTERPRISE ADVANTAGES

企业优势

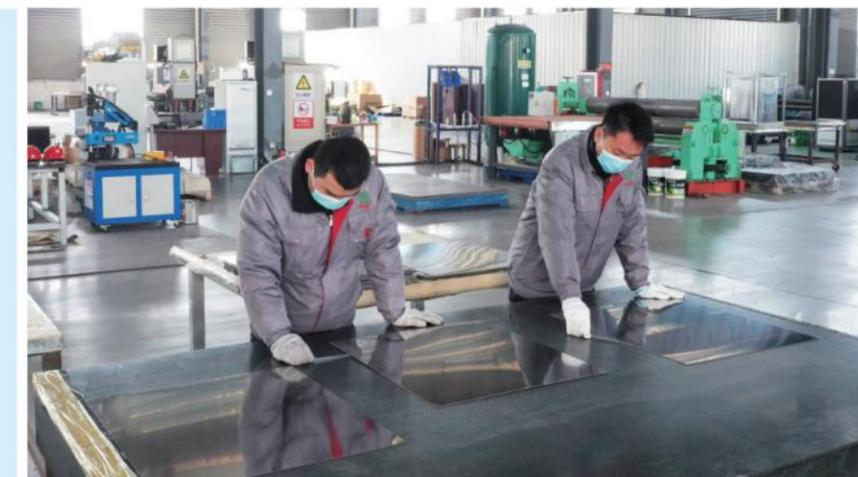


专业工艺标准

Professional process standards

产品严苛的工艺标准，完善的
生产流程，质量安全可靠，精密制造，结实耐用。

The product has strict process standards, perfect production processes, reliable and safe quality, precision manufacturing, and is sturdy and durable.



优质原材料

High quality raw materials

使用自主生产的优质原材料，经过层层筛选，严苛的工艺标准，完善的
生产流程，质量安全可靠，结实耐用。

Using high-quality raw materials produced independently, after layers of screening, strict process standards, perfect production processes. Quality, safety, reliability, and durability.

压合耐高温材料·我们更专业

专注产品品质·实力成就未来·提供性价比产品

We are more professional in laminating high-temperature resistant materials
Focus on product quality, strength for the future, and provide cost-effective products

配送及时

Timely delivery

配送方式多种多样，根据货物的性质，数量和收货方的要求，选择合适的配送方式

There are various delivery methods available, and the appropriate delivery method should be selected based on the nature, quantity, and requirements of the recipient





**PRODUCTION
WORKSHOP**
生产车间

PRODUCTION WORKSHOP

生产车间

匠心独运 打造品质之美

Crafted with ingenuity to
create the beauty of quality



PRODUCTION WORKSHOP

生产车间



压机
PRESS

我们拥有一流的高级设备及专业的技术团队
为您打造高质量的产品

We have first-class advanced equipment and a professional technical team to
create high-quality products for you



上胶线
GLUE LINE



裁磨线
GRINDING LINE



叠板线
STACKING LINE



压合材料 竹浆牛皮纸

COMPRESSION MATERIAL
**BAMBOO PULP
KRAFT PAPER**



产品介绍 Product introduction

由竹浆经特殊工艺加工制成，厚度均匀性更好，有独特的传热稳定性，比常用的木浆牛皮纸更耐高温，同时不粘连钢板、不易碳化 and 掉屑，可满足无铅化焊接需要，可抵御 220°C 高温。

Made from bamboo pulp processed by special techniques, it has better thickness uniformity, unique heat transfer stability, and is more resistant to high temperatures than commonly used wood pulp and kraft paper. At the same time, it does not adhere to steel plates, is less prone to carbonization and chip shedding, and can meet the needs of lead-free welding. It can withstand high temperatures of 220 °C .



物理参数 Physical parameters

对比项目 Compare projects	竹浆牛皮纸 Bamboo pulp kraft paper	木浆牛皮纸 Wood pulp kraft paper
使用次数 Compare projects	4 次 /times	4 次 / times
厚度公差 Number of uses	±0.03mm	±0.03mm
吸水率 Tolerance	3%-8%	3%-8%
克重 Grammage	160g/190g/250g/320g	160g/190g/250g/320g
物质含量 Substance Content	食用级 food grade	/
杂质含量 Impurity content	无尘级 Dust free grade	非无尘级 Non dust-free grade
是否粘钢板 Is it sticky steel plate	0 机率粘钢板 0 chance of sticking steel plate	/
钢板是否残留异物 Is there any foreign body left on the steel plate?	无异物 No foreign objects	/
耐热性 Heat resistance	上限 220° C Upper limit 220 ° C	上限 215° C Upper limit 215 ° C



高温缓冲材料 纳维斯垫

HIGH TEMPERATURE BUFFER MATERIAL

NAWES MAT



产品介绍 Product introduction

为适应电子行业新的 5G 材料与高标准的压合条件，及遵循行业内的环保趋势，我司研发人员经多年研制与创新，特推出可取代牛皮纸的高温缓冲材料 -- **纳维斯垫**。

In order to adapt to the new 5G materials and high standard bonding conditions in the electronics industry, and to follow the environmental trend in the industry, our R&D personnel have developed and innovated for many years, and have specially launched a high-temperature cushioning material - NAWES MAT - that can replace kraft paper.



物理参数 Physical parameters

	纳维斯缓冲垫 NAWES MAT	牛皮纸 KRAFT PAPER
产地 Origin	中国 China	中国 China
品名 Product Name	缓冲垫 Cushion	牛皮纸 Kraft paper
材质 Material	高弹性纤维 + 氟树脂 High elasticity fiber+fluororesin	植物纤维 + 浆 Plant fiber+pulp
厚度 Thickness (mm)	1.2 ~ 12	0.23
缓冲性 Buffer capacity (%)	≥ 16	≥ 8
耐高温 Temperature resistance (°C)	≤ 260	≤ 220
水分含量 Moisture content (%)	≤ 7	≤ 8
使用次数 Usage frequency (times)	300 ~ 500	1 ~ 4
热阻 Thermal resistance (K * M2/W)	0.01159	0.02084
热传导率 Thermal conductivity W/(m * k)	0.311	0.173

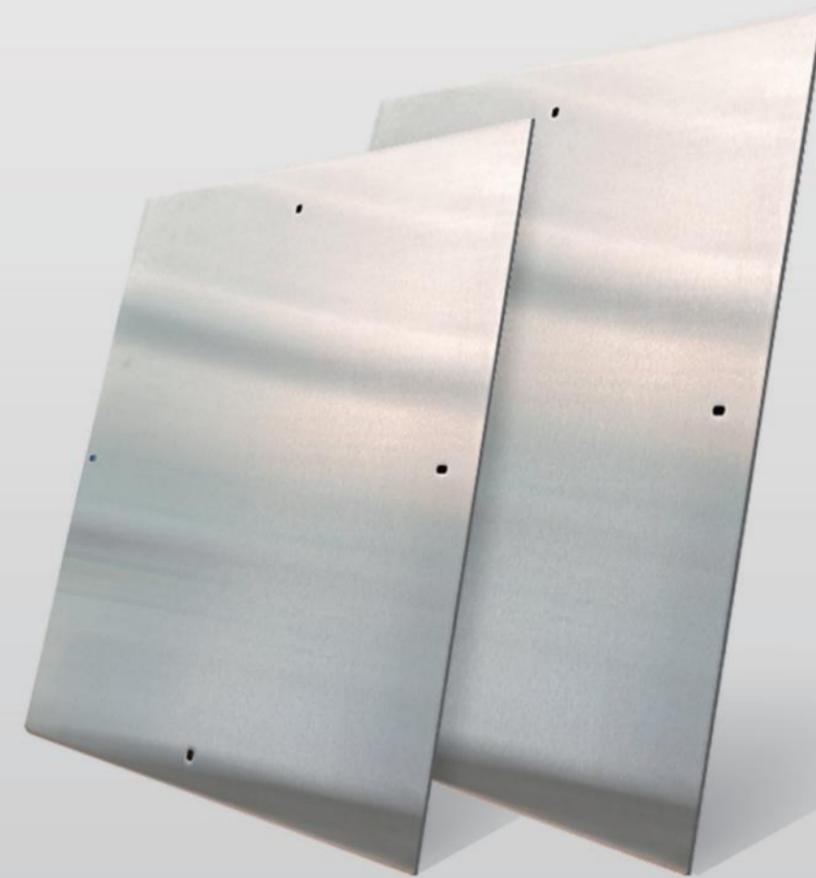




压合进口镜面钢板

PRESS FIT IMPORTED

MIRROR STEEL PLATE



产品介绍 Product introduction

主要代理日本冶金和德国镜面钢板（原装进口），包含 NAS630&NAS301（高膨胀系数）和 4120&4310（高膨胀系数）析出硬化钢板四种，可满足行业内性能要求。优点：成本低、平行度高、交期短、可打通孔二维码实现后期追溯、配备更快捷的技术服务。

We mainly act as agents for Japanese metallurgy and German mirror steel plates (imported with original equipment), including four types of NAS630&NAS301 (high expansion coefficient) and 4120&4310 (high expansion coefficient) precipitation hardening steel plates, which can meet the performance requirements of the industry. Advantages: Low cost, high parallelism, short delivery time, able to access QR codes for later traceability, equipped with faster technical services.

加工精度 Machining accuracy

	MASSLAM	PINLAM
长宽公差 Length and width tolerance (mm)	±0.5	±0.5
厚度公差 Thickness tolerance (mm)	±0.05	±0.05
平行度 Parallelism (mm)	≤ 0.03	≤ 0.03
平整度 Flatness (mm/m)	≤ 3	≤ 3
粗糙度 Roughness (um)	Rz ≤ 1.5、Ra ≤ 0.15	Rz ≤ 1.5、Ra ≤ 0.15
定位孔的对孔公差 Positioning hole tolerance (mm)	/	±0.02
标准衬套槽孔公差 Standard bushing slot tolerance (mm)	/	±0.02

物理参数 Physical parameters

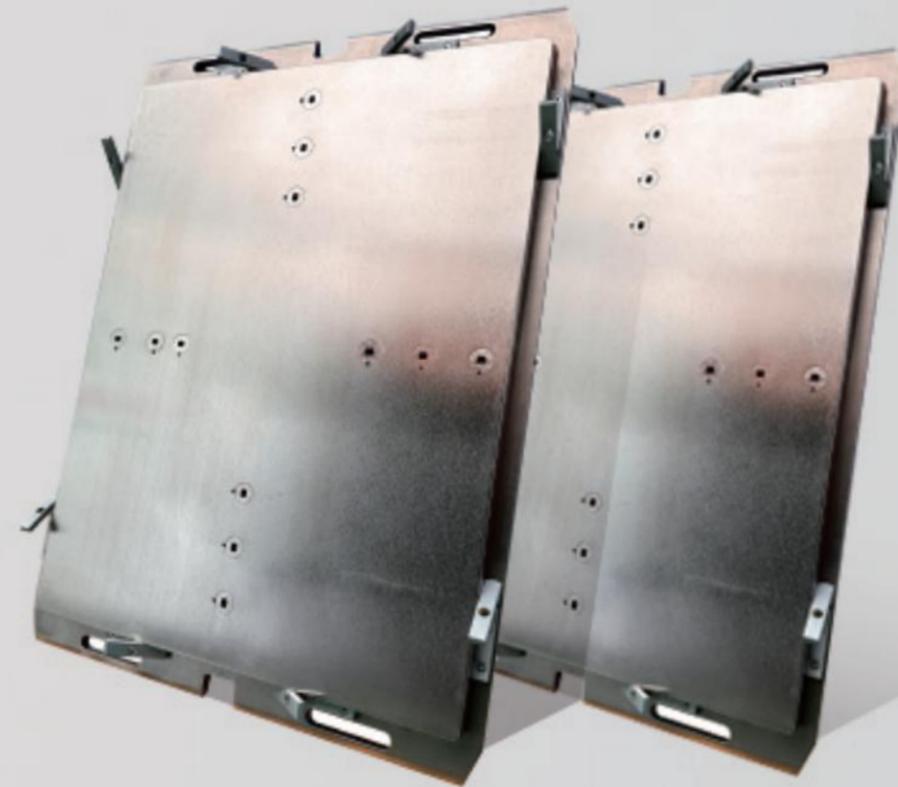
压合进口镜面钢板 Press fit imported mirror steel plate				
产地 Origin	德国 Germany		日本 Japan	
品名 Product Name	Outokumpu		NAS	
材质 Material	4120	4310	630	301
厚度 Thickness (mm)	1.0 ~ 2.0	1.0 ~ 2.0	1.0 ~ 2.0	1.0 ~ 2.0
硬度 Hardness (HRC)	50±2	45±2	49±2	44±2
屈服强度 Yield strength (N/mm ²)	≥ 1100	≥ 1000	≥ 1400	≥ 1000
抗拉强度 Tensile strength (N/mm ²)	≥ 1500	≥ 1300	≥ 1500	≥ 1300
延展性 Ductility (%)	≥ 5	≥ 5	≥ 5	≥ 5
平均热膨胀系数 Average coefficient of thermal expansion (10-6/°C)	10 ~ 12	15 ~ 17	10 ~ 12	15 ~ 17
热传导率 Thermal resistance (K * M2/W)	17 ~ 25	17 ~ 25	17 ~ 25	17 ~ 25
工作温度 Working temperature (°C)	≤ 400	≤ 400	≤ 400	≤ 400



压合进口 承载盘 / 盖板

PRESS FIT IMPORTED

CARRYING PLATE/COVER PLATE



产品介绍 Product introduction

主要代理德国 DILLIDUR-450 和瑞典 HARDOX-450 两种进口承载盘 / 盖板，可满足 MASSLAM 和 PINLAM 两种加工精度，同时性能也可满足行业内各种要求。

We mainly act as agents for two imported bearing discs/covers, DILLIDUR-450 from Germany and HARDOX-450 from Sweden, which can meet the machining accuracy of MASSLAM and PINLAM, and the performance can also meet various requirements in the industry.

加工精度 Machining accuracy

	MASSLAM	PINLAM
长宽公差 Length and width tolerance (mm)	±0.5	±0.5
厚度公差 Thickness tolerance (mm)	±0.2	±0.05
平行度 Parallelism (mm)	≤ 0.1	≤ 0.03
平整度 Flatness (mm/m)	≤ 3	≤ 0.5
粗糙度 Roughness (um)	Rz ≤ 10、Ra ≤ 1	Rz ≤ 8、Ra ≤ 0.8
定位孔的对孔公差 Positioning hole tolerance (mm)	/	±0.02
标准衬套槽孔公差 Standard bushing slot tolerance (mm)	/	±0.02

物理参数 Physical parameters

压合进口承载盘 / 盖板 Press fit imported bearing disc/cover plate		
产地 Origin	德国 Germany	瑞典 Sweden
品名 Product Name	DILLIDUR	HARDOX
材质 Material	450	450
厚度 Thickness (mm)	8 ~ 100	3 ~ 80
硬度 Hardness (HBW)	450±30	450±25
屈服强度 Yield strength (N/mm ²)	≥ 1000	≥ 1200
抗拉强度 Tensile strength (N/mm ²)	≥ 1250	≥ 1400
延展性 Ductility (%)	≥ 10	≥ 10
平均热膨胀系数 Average coefficient of thermal expansion (10-6/°C)	≥ 10	≥ 10
热传导率 Thermal resistance (K * M2/W)	≥ 42	≥ 42
工作温度 Working temperature (°C)	≤ 400	≤ 400

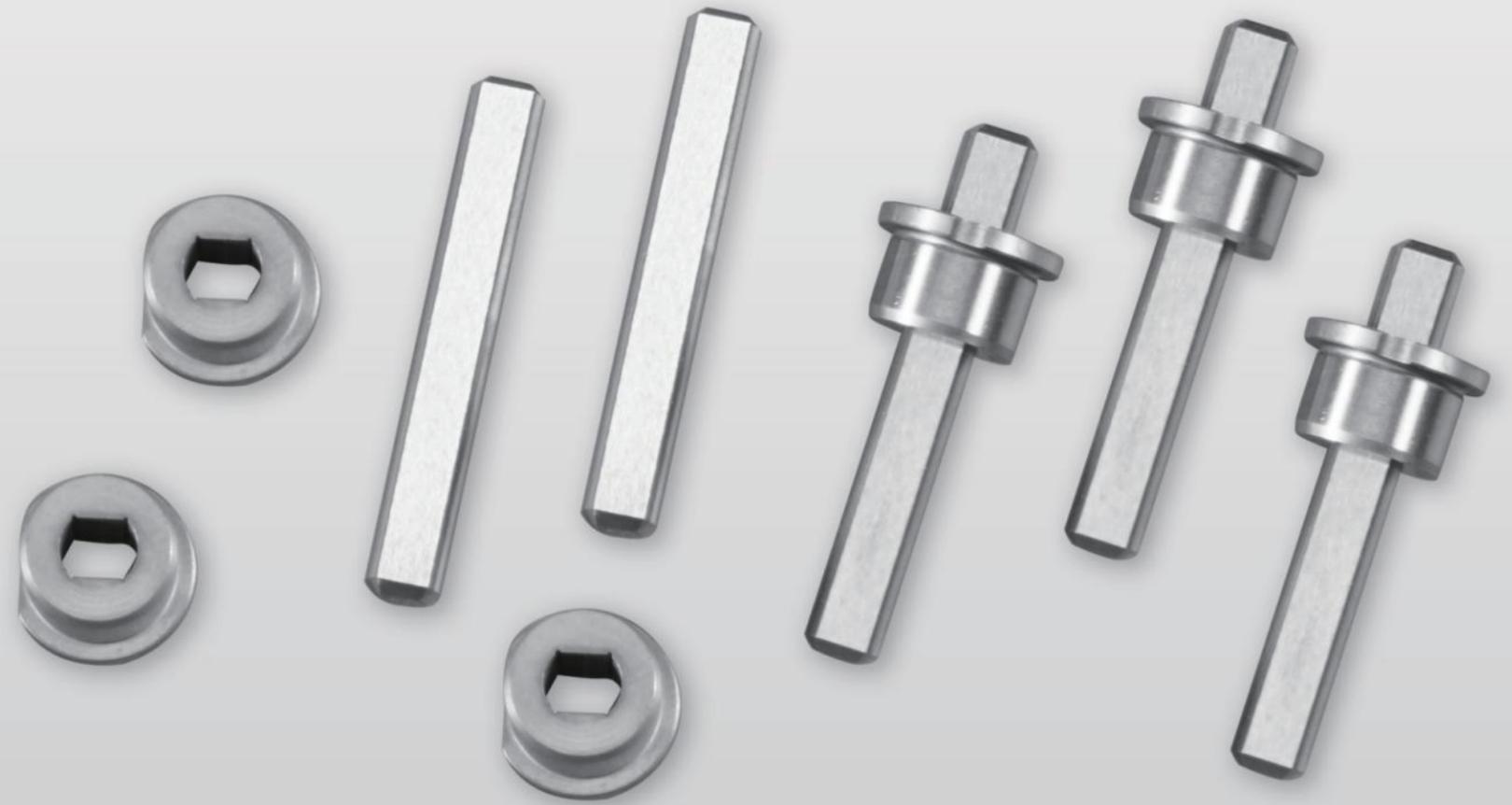


压合进口

PIN 钉 /PIN 套

PRESS FIT IMPORTED

PIN NAIL/PIN SET



产品介绍 Product introduction

本品采用日本进口钢材制作，可满足客户硬度、精度等各种要求。

This product is made of imported steel from Japan, which can meet various customer requirements such as hardness and accuracy.



加工精度 Machining accuracy

产品特性 Product characteristics	SKD-11			
	PIN 钉 PIN nail		PIN 套 PIN sleeve	
	圆形 Rotundity	方形 Square	圆形 Rotundity	方形 Square
长度 Length (mm)	19、25、32、35、38、44、51、57、63	19、25、32、35、38、44、51、57、63	9.532	9.532
直径公差 Diameter tolerance (mm)	-0.01/-0.005	-0.01/-0.005	-0.08/-0	-0.08/-0
宽度公差 Width tolerance (mm)	/	-0.01/-0.005	/	+0.02/+0.025
标准槽孔 Standard slot (mm)	/	/	15.57	15.57
硬度 Hardness (HRC)	60±2	60±2	60±2	60±2
备注 Notes	可根据客户需求进行配规 Can be customized according to customer needs			



压合材料 耐高温哑光离型膜

COMPRESSION MATERIAL

HIGH TEMPERATURE RESISTANT MATTE RELEASE FILM



产品介绍 Product introduction

耐高温哑光离型膜厚度有 25um、30um、36um、50um、75um、100um 等，本品采用 PET 改性膜进行抗高温特性添加剂加工而成，使得该产品具有较好的耐高温性能，同时压合后表面无残留，为柔性和刚性电路板的生产场合设计和制造。

The thickness of the high-temperature resistant matte release film includes 25um, 30um, 36um, 50um, 75um, 100um, etc. This product is made by processing PET modified film with high-temperature resistant additives, which makes the product have good high-temperature resistance performance. At the same time, there is no residue on the surface after compression, which is designed and manufactured for the production of flexible and rigid circuit boards.



物理参数 Physical parameters

指标名称 Indicator Name	指标值 Indicator Value	测试方法 Test Method
耐温度 Temperature resistance(°C)	≤ 240	/
熔点 Melting point(°C)	250-260	/
分解温度 Decomposition temperature(°C)	> 300	/
收缩率 Shrinkage rate(%)	纵向 / 横向 Portrait/Landscape ≤ 2	BMSTT11(150°C /30MIN)
燃点 Flash point(°C)	350(密闭)Colour	/
自燃温度 Auto-ignition temperature(°C)	> 420	/
拉伸强度 Tensile strength (Mpa)	MD 纵向 Portrait > 140、TD 横向 Landscape > 180	DIN53455-6-5
断裂伸长率 Rlongation at break(%)	MD 纵向 Portrait < 150、TD 横向 Landscape < 100	DIN53455-6-5
离型力 Release force(gf)	8-20	ASTM D3330
毒副性和安全性 Toxicity and safety	无毒、安全 Non toxic and safe	/
厚度公差 Tolerance(mm)	±0.003mm	DIN53370
颜色 Colour	哑光 Matte	目测 Visualization
氧化性 Oxidability	根据欧洲共同体的标准，本产品为非氧化性物质。 According to the standards of the European Community, this product is a non oxidizing substance	



压合材料 三合一离型膜

COMPRESSION MATERIAL

THREE IN ONE RELEASE FILM



产品介绍 Product introduction

对于多层板、软硬结合板等高低落差较大的电路板，在其压合过程中，三合一离型膜较普通离型膜，阻胶、填充能力更佳。由于其芯层（覆型膜）在高温作用下，流动性更大，可以有效解决市场上其他品牌易出现的侧面溢胶、漏胶问题，提升了压合产品品质，大大减少清洁成本，提高生产效率。

For circuit boards with large high-low pressure differences such as multi-layer boards and soft hard bonding boards, the three in one release film has better resistance and filling ability than ordinary release films during the pressing process. Due to its core layer (coating film) having greater fluidity under high temperature, it can effectively solve the problems of side overflow and leakage that other brands are prone to in the market, improve the quality of pressed products, greatly reduce cleaning costs, and improve production efficiency.



应用参数 Reference parameter

1. 建议压合温度 $\leq 200^{\circ}\text{C}$ ，压合最高温度为 220°C 。
2. 三合一与钢板接触的表层厚度 $\geq 50\mu\text{m}$ ，与电路板接触的表层厚度 $\geq 36\mu\text{m}$ 。
3. 常规 PE 芯层边沿到表层边沿至少 $> 20\text{mm}$ 。
4. 可以根据电路板的厚度来建议客户使用不同厚度的芯层例如，0.15mm 厚的电路板，芯层厚度只需 0.15mm 即可。
5. 三合一的铆合方式为超声波铆合和双面胶带或者胶水贴合如果客户不明确要求，可以优先测试超声波铆合的样品。

1. It is suggested that the pressing temperature should be $\leq 200^{\circ}\text{C}$ and the highest pressing temperature should be 220°C .
2. The surface thickness of the three-in-one contact with the steel plate is $\geq 50\mu\text{m}$, and the surface thickness of the three-in-one contact with the circuit board is $\geq 36\mu\text{m}$.
3. The edge of the conventional PE core layer to the edge of the surface layer is at least $> 20\text{mm}$.
4. According to the thickness of the circuit board, customers can be advised to use core layers with different thicknesses, for example, a circuit board with a thickness of 0.15mm, and the core layer thickness is only 0.15 mm.
5. The three-in-one riveting method is ultrasonic riveting and double-sided tape or glue bonding. If the customer does not explicitly require it, the ultrasonic riveting sample can be tested first.

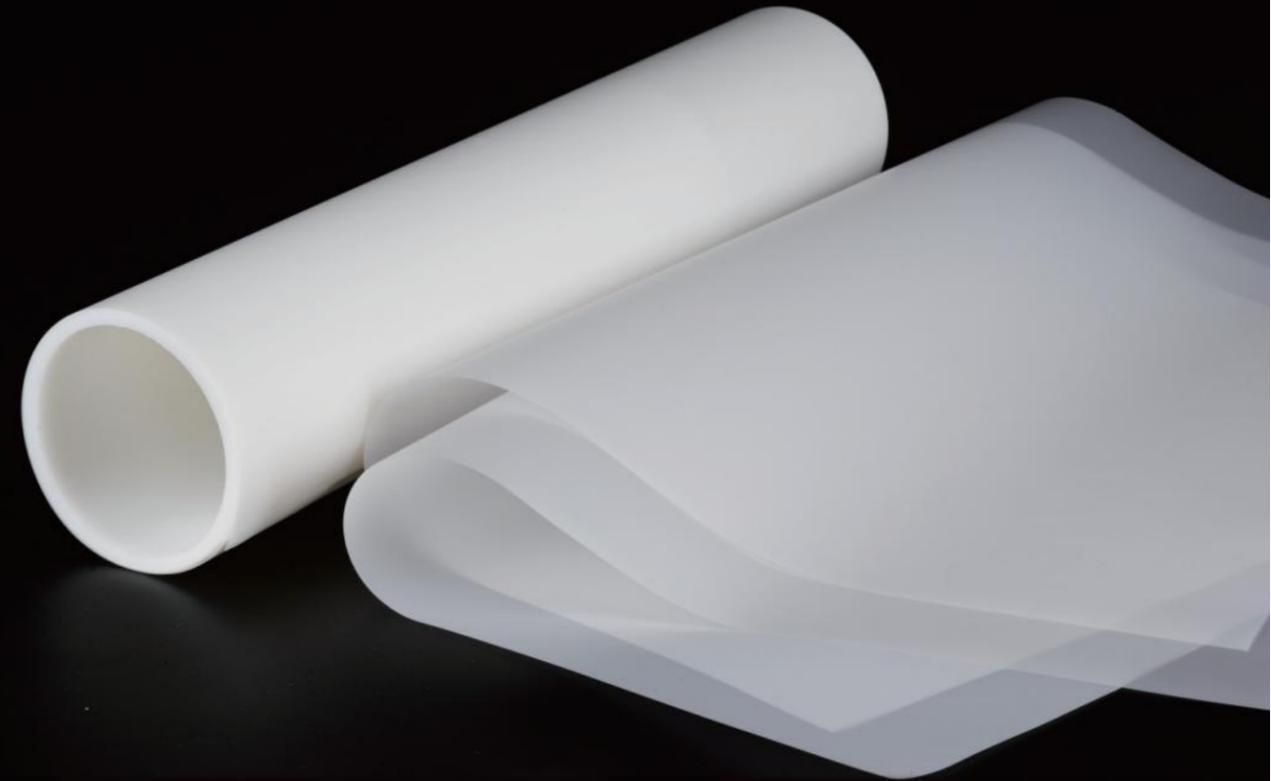


压合材料

TPX 膜 (阻胶膜)

COMPRESSION MATERIAL

TPX FILM (ADHESIVE BARRIER FILM)



产品介绍 Product introduction

本品通过聚酯树脂、聚乙烯树脂等聚合而成，具有优秀的耐热性（200℃）、缓冲性、离型性、阻胶性及涨缩均一性等性能。

This product is polymerized from polyester resin, polyethylene resin, and other materials, and has excellent properties such as heat resistance (200 °C), buffering, release, adhesive resistance, and uniformity of expansion and contraction.



物理参数 Physical parameters

项目 Project		数值 Numerical Value	公差 Public Errand	备注 Notes
尺寸 Size	厚度 Thickness	120um、150um、190um	10%	测厚仪 Thickness gauge
	长度 Length	500m	±2m	卷尺 Tape measure
	宽度 Width	270mm、520mm	±2mm	直尺 Ruler
熔点 Melting point	外层 Outer layer	210°C	±5°C	熔点仪 Melting point meter
	内层 Inner layer	100°C	±5°C	
拉伸强度 Tensile strength	MD	30MPa	±5MPa	电子万能材料试验机 Electronic universal material testing machine
	TD	20MPa	±5MPa	
尺寸稳定性 Dimensional stability	MD	2.1%	≤ 4%	分析仪 Analyzer
	TD	1.7%	≤ 2.5%	
密度 Density		1.05g/cm ³	0.9 ~ 1.1g/cm ³	密度仪 Densitometer
雾度 Haze ratio		3.2%	±0.5%	透光率雾度测定仪 Light transmittance haze tester
光泽度 Gloss		125%	±10%	光泽度仪 Glossmeter
介电强度 Dielectric strength		65KV/mm	±5KV/mm	介电强度仪 Dielectric strength meter

COOPERATIVE PARTNER

合作伙伴



互利共赢 携手成长

诚挚感谢每一位合作伙伴的信任与支持！让我们继续携手，以更加开放的态度，更加紧密的合作，共同开创属于我们的辉煌未来！

MUTUAL BENEFIT AND WIN-WIN GROWING TOGETHER

Sincere thanks to every partner for their trust and support! Let us continue to work hand in hand, with a more open attitude and closer cooperation, to jointly create a brilliant future that belongs to us!

CCL



PCB



FUTURE DEVELOPMENT

未来发展



建立研发、制造、销售及售后 密切结合的经营体系

Establish a business system that closely integrates research and development, manufacturing, sales, and after-sales service



优化产品结构
提升产品市场竞争力
完善服务配套体系

Optimize product structure
Enhance product market competitiveness
Improve the service supporting system

公司将在现有业务基础上，依托研发团队和技术实力，继续保持技术领先，加大缓冲垫研究力度和市场拓展力度，完善产品和服务配套体系，继续扩大公司主营产品市场推广力度，进一步加强公司营销网络的建设；同时继续优化产品结构，提升产品市场竞争力，扩大经营规模，建立研发、制造、销售及售后密切结合的经营体系。此外公司还将加强企业文化建设，健全企业治理结构，实现客户、员工与公司的共同发展。

On the basis of its existing business, the company will rely on its R&D team and technical strength to continue to maintain technological leadership, increase research and market expansion efforts on cushioning pads, improve product and service supporting systems, continue to expand the market promotion of the company's main products, and further strengthen the construction of the company's marketing network; At the same time, we will continue to optimize our product structure, enhance our market competitiveness, expand our business scale, and establish a business system that closely integrates research and development, manufacturing, sales, and after-sales service. In addition, the company will strengthen the construction of corporate culture, improve corporate governance structure, and achieve the common development of customers, employees, and the company.